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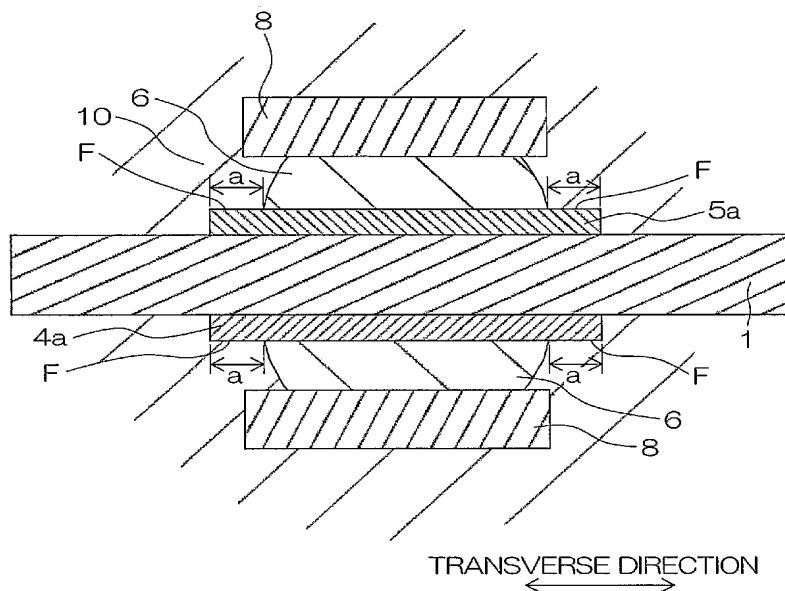
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(54) Title: SOLAR CELL MODULE



(57) Abstract: The largest stress is created in the vicinity of the boundary between an edge of a bus bar electrode in a solar cell and a surface of a semiconductor substrate, and stresses are easily concentrated. Accordingly, defects such as micro cracks occur in the semiconductor substrate, which develop into a large craze with the defects as its starting point. In connecting bus bar electrodes 4a and 5a in the solar cell by an inner lead 8, therefore, a solder 6 is not brought into contact with edges along the longitudinal direction of the bus bar electrodes 4a and 5a and portions F from the edges to a predetermined distance inward therefrom, and is brought into direct contact with a filler 10.

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